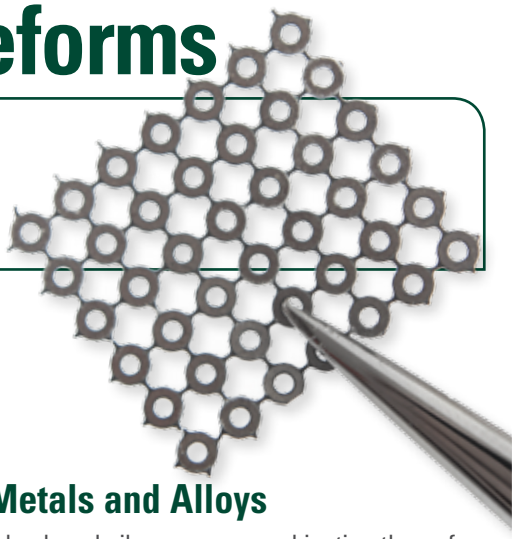
PRODUCT DATA SHEET

InTEGRATED® Solder Preforms

Introduction

InTEGRATED® SOLDER PREFORMS are joined in a matrix by fine, precise strands of solder which, during the soldering process, melt and flow to adjacent pads to give you complete preform separation.



Applications

InTEGRATED® Solder Preforms save assembly time and labor costs by allowing simultaneous placement of all the solder preforms needed on connector pins, pin grid arrays (PGAs), and other multiple-pad/pin components. They solve both assembly and product design challenges by allowing users to specify fabrications in the most complex arrays, including those which would be impossible or cost-prohibitive to produce by conventional methods. Arrays can even be designed with built-in frames to improve handling in manual assembly processes.

InTEGRATED® Solder Preforms can also be used in non-array configurations for applications, such as vacuum/cryogenic sealing and other mechanical assembly operations.

Array Pitch Tolerance-Non-Accumulative

Center-to-center accuracy can be held to +/-.0002".

Physical Dimensions

Because specification limitations vary by alloy, preform thickness, shape, and other considerations, please consult with our sales or technical staff for recommendations related to your specific application.

Standard Dimensions

Alloy	OD	ID	Thickness	Pitch
SAC305	0.080	0.040	0.010	0.1000
Sn63	0.080	0.040	0.010	0.1000
SAC305	0.080	0.040	0.015	0.1000
Sn63	0.080	0.040	0.015	0.1000
SAC305	0.080	0.040	0.020	0.1000
Sn63	0.080	0.040	0.020	0.1000

Alloy	OD	ID	Thickness	Pitch
SAC305	0.060	0.033	0.010	0.0787
Sn63	0.060	0.033	0.010	0.0787
SAC305	0.060	0.033	0.015	0.0787
Sn63	0.060	0.033	0.015	0.0787

Dimensions are in inches.

Available Metals and Alloys

Pure indium, tin, lead, and silver, or any combination thereof, can be made into **InTEGRATED® Solder Preforms**. Upon request, other metals and alloys will be evaluated for their applicability to **InTEGRATED® Solder Preforms** technology.

Reflow Methods

InTEGRATED® Solder Preforms are compatible with most reflow methods, such as I/R, laser, vapor phase, conduction, convection, or hot-air guns.

Packaging

Standard packaging consists of rigid-board folders in argon-filled poly bags. Custom packaging is available upon request.

Shelf Life

The shelf life of solder preforms is dependent upon the alloy composition. Pb-free alloys and alloys with lead content of <50% have a shelf life of one year from the date of manufacture (DOM). Alloys with lead content ≥50% have a shelf life of six months from the DOM.

Technical Support

Indium Corporation's internationally experienced engineers provide in-depth technical assistance to our customers. Thoroughly knowledgeable in all facets of Material Science as it applies to the electronics and semiconductor sectors, Technical Support Engineers provide expert advice in solder properties, alloy compatibility, and selection of solder preforms, wire, ribbon, and paste. Indium Corporation Technical Support engineers provide rapid response to all technical inquiries.

Safety Data Sheets

The SDS for this product can be found online at http://www.indium.com/sds

Also available: solder preforms, solder wire, solder ribbon and foil, solder paste, solder spheres, solder fluxes, solder ingot, and other solder fabrications.

Contact our engineers today: **askus@indium.com**
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